



Advanced Echem Materials Company Ltd.

(Stock code : 4749)

Investor Conference



March 12, 2026

Safe Harbor Notice

- AEMC's statements of its current expectations are forward-looking statements subject to significant risks and uncertainties and actual results may differ materially from those contained in the forward-looking statements.
- AEMC makes no representation or warranty regarding such forward-looking statements. Except as required by law, AEMC undertakes no obligation to update any forward-looking statements, whether as a result of new information, future events, or otherwise.

Agenda

- Company Overview
- Main Products and Markets
- Product Roadmap
- Financial Highlights
- ESG Performance
- Appendix

Our Mission and Vision

Mission

Establish upstream and downstream supply chains

Our mission is to establish Taiwan's independent technology in specialty chemicals for advanced semiconductor processes and through collaboration, enhance the global competitiveness of the local specialized materials industry, both upstream and downstream.

Vision

Expand the variety of lithography materials and increase market share

Our vision is to enhance Synthesis, Purification, Formulation, and process technologies to meet customer needs, assist in yield improvement deliver exceptional added value, and become an innovative specialty chemical company with global competitiveness.

Awards

TSMC Excellent Performance Award, 2022 Excellent Material Development and Production Support in Litho Materials
National Industrial Innovation Award, 2023

About AEMC



Paid-in Capital : NT\$926M / US\$30.8M
Number of Employees : 456 (2025.12)
R&D Personnel : 135 (2025.12)

Main Products

- Specialty Materials for Semiconductors
 - Advanced Process Materials
 - Advanced Packaging Materials
 - Optical Component Materials
- Specialty Materials for Displays
 - Display Photoresist

Locations

Taoyuan Factory - HQ with R&D Center : Display Specialty Chemicals 、
Optical Component Materials
Tainan Factory : Semiconductor Specialty Chemicals
Kaohsiung Factory : Semiconductor Specialty Chemicals

Invested Companies

AEMC JAPAN Corporation (Subsidiary 100%)
AEMC USA Corporation (Subsidiary 100%)
SCIWIN (Subsidiary 70%)
Oleader Technologies (Equity investment 48%)
e-Ray Technology (Equity investment 29.985%)
Advanced Pao Trusval Technology (Equity investment 36%)

About AEMC



2003

Photoresist for Display

2014

Materials for Semiconductor Optical Components

2018

Materials for Advanced Semiconductor Processes

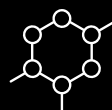
2025

Photoresist for Advanced Semiconductor Processes

2026

Materials for Advanced Packaging

Main Products



Semiconductor Specialty Chemicals

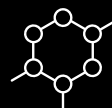
-Advanced Lithography Process

- Rinse
- EBR
- Cleaner
- BARC

-Advanced Packaging Material

-Optical Component

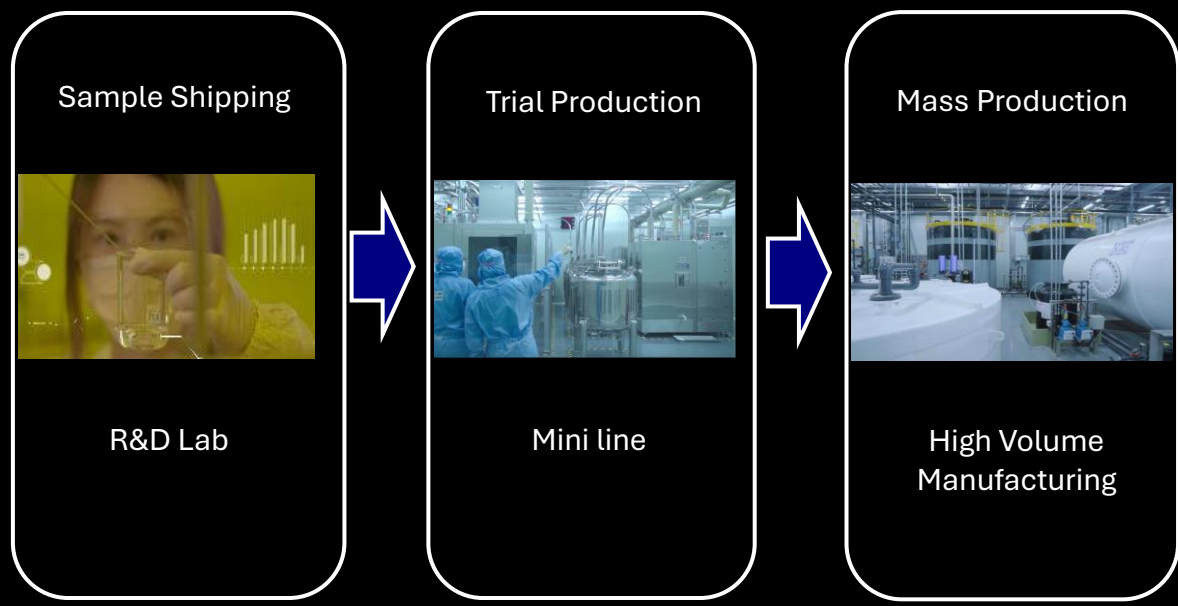
- Image Sensor Material
- Micro-Optical Component Material



Display Specialty Chemicals

-Display Photoresist

R&D and Production Sites



Longtan Science Park Factory

R&D Center, Semiconductor
Specialty Materials

Scheduled for Completion in Early 2028

Taoyuan Factory

Display Specialty Chemicals
Optical Component Materials

Tainan Factory

Semiconductor
Specialty Chemicals

Kaohsiung Factory

Semiconductor Specialty
Chemicals



Major Customer's Advanced Process Capacity Roadmap



Sites	Node	2025	2026	2027	2028
Tainan	3nm				
Hsinchu	2nm/1.6nm				
Kaohsiung					
Tainan					
Hsinchu	1.4nm				
Taichung					
Arizona, USA	4nm~2nm				
Kumamoto, Japan	3nm				

Source: Aletheia / TAG, Business Next, and Company Consolidation

Agenda

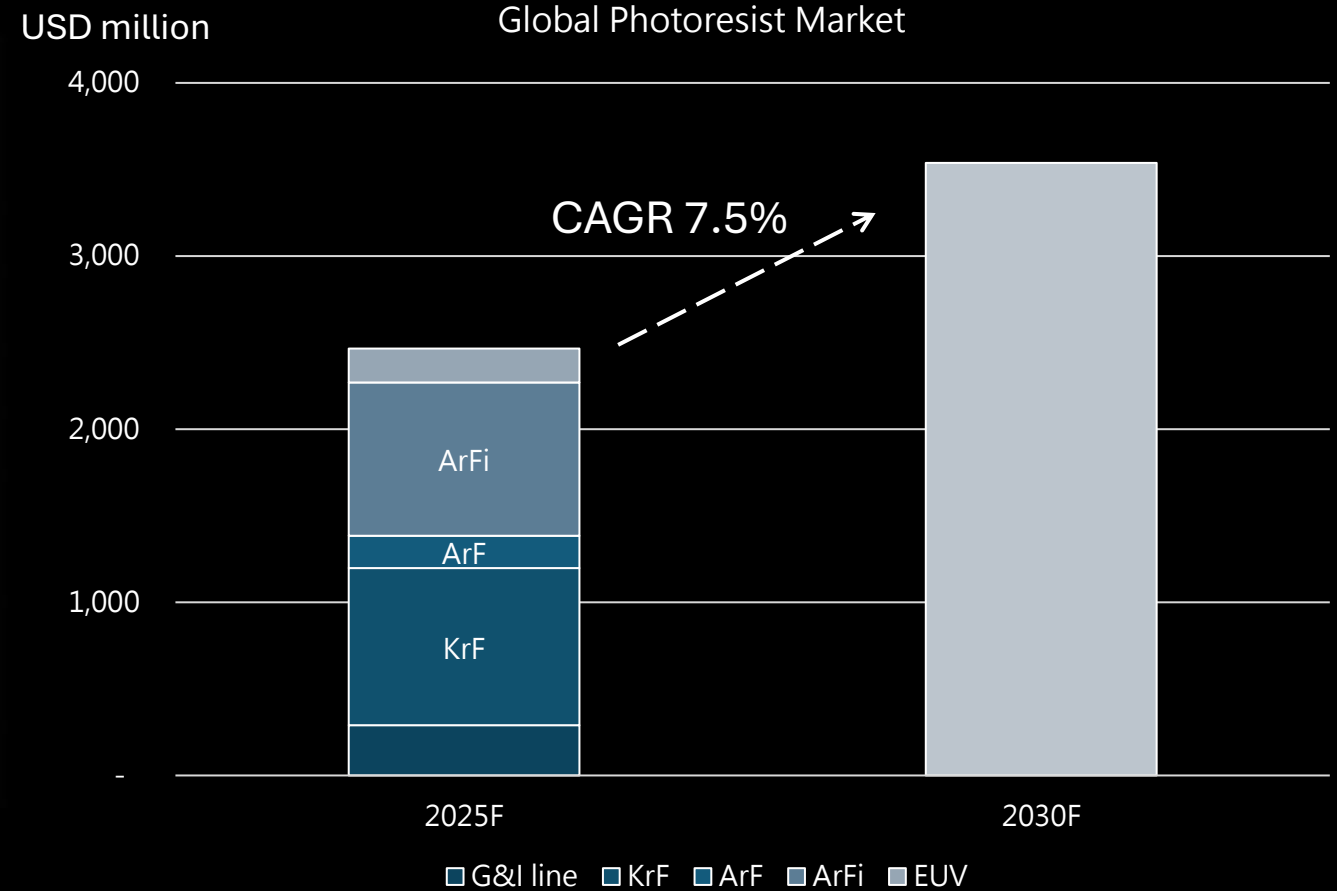
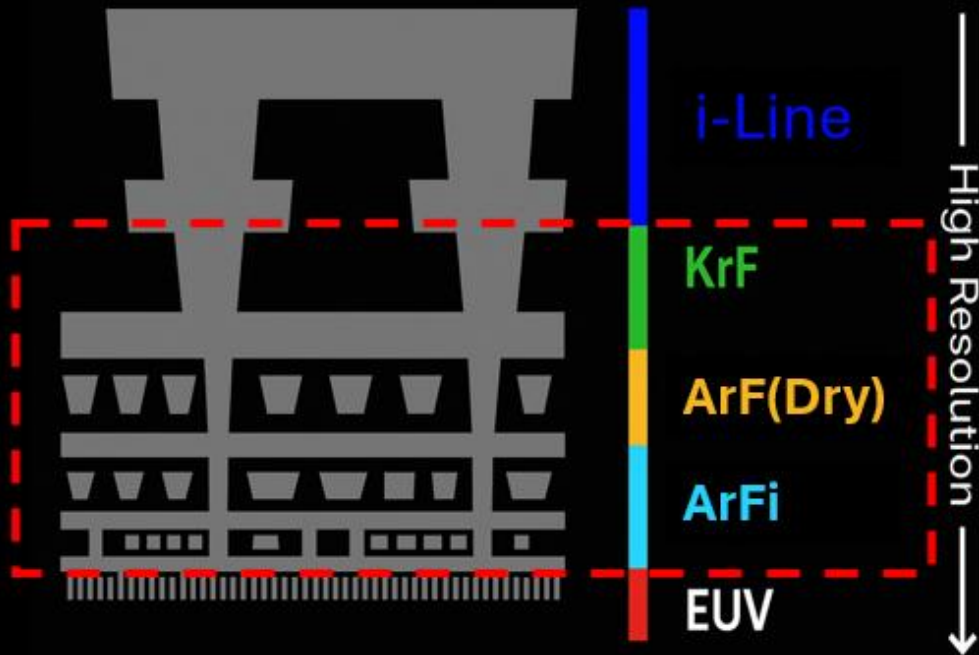
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R&D Roadmap



Application Field	Mass Production	Verification	Developing
Advanced Microlithography Materials	<ul style="list-style-type: none"> • Rinse Material (潤濕液) • BARC (底部抗反射層) • EBR (晶邊清洗劑) • Cleaner (清洗劑) 	<ul style="list-style-type: none"> • Rinse Material for next node • BARC for next node • EBR for next node • Cleaner for next node • DUV Photoresist (KrF) 	<ul style="list-style-type: none"> • Bottom Layer for next node • Advanced BARC • Protection Layer • DUV Photoresist (ArF)
Advanced Packaging Materials	<ul style="list-style-type: none"> • Temporary Protection Layer • Plasma Dicing Glue 	<ul style="list-style-type: none"> • Protection Layer for SoIC • KrF BARC • Cleaner • Protection Glue for CPO • Leveling Layer 	<ul style="list-style-type: none"> • High AR Photoresist • Packaging Glue • Photoresist for Fine pitch QFN
Optical Element Materials	<ul style="list-style-type: none"> • Photoresists (光阻劑) • Flat Layer (平坦層) • Color Filter Layer (濾光層) • Light-cut Layer (遮光層) • Lift-off Layer(離型層) 	<ul style="list-style-type: none"> • DUV Photoresist (ArF) • Stripper • Liff-off Layer for next node • ArF BARC • Adhesion Layer 	<ul style="list-style-type: none"> • Leveling Layer • Microlens Materials

Advanced Lithography Materials Photoresist



Source: TECHCET(2021) 、 WSTS(2024) 、 Deloitte(2025) 、 Estimate by Company

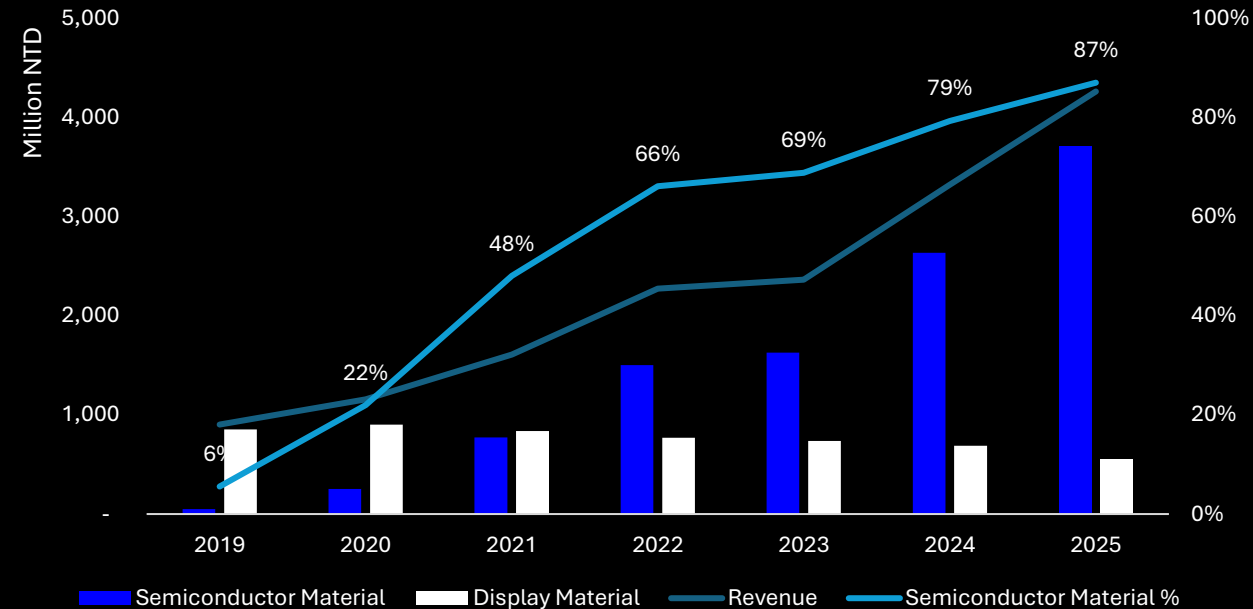
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Financial Highlights



Financial results

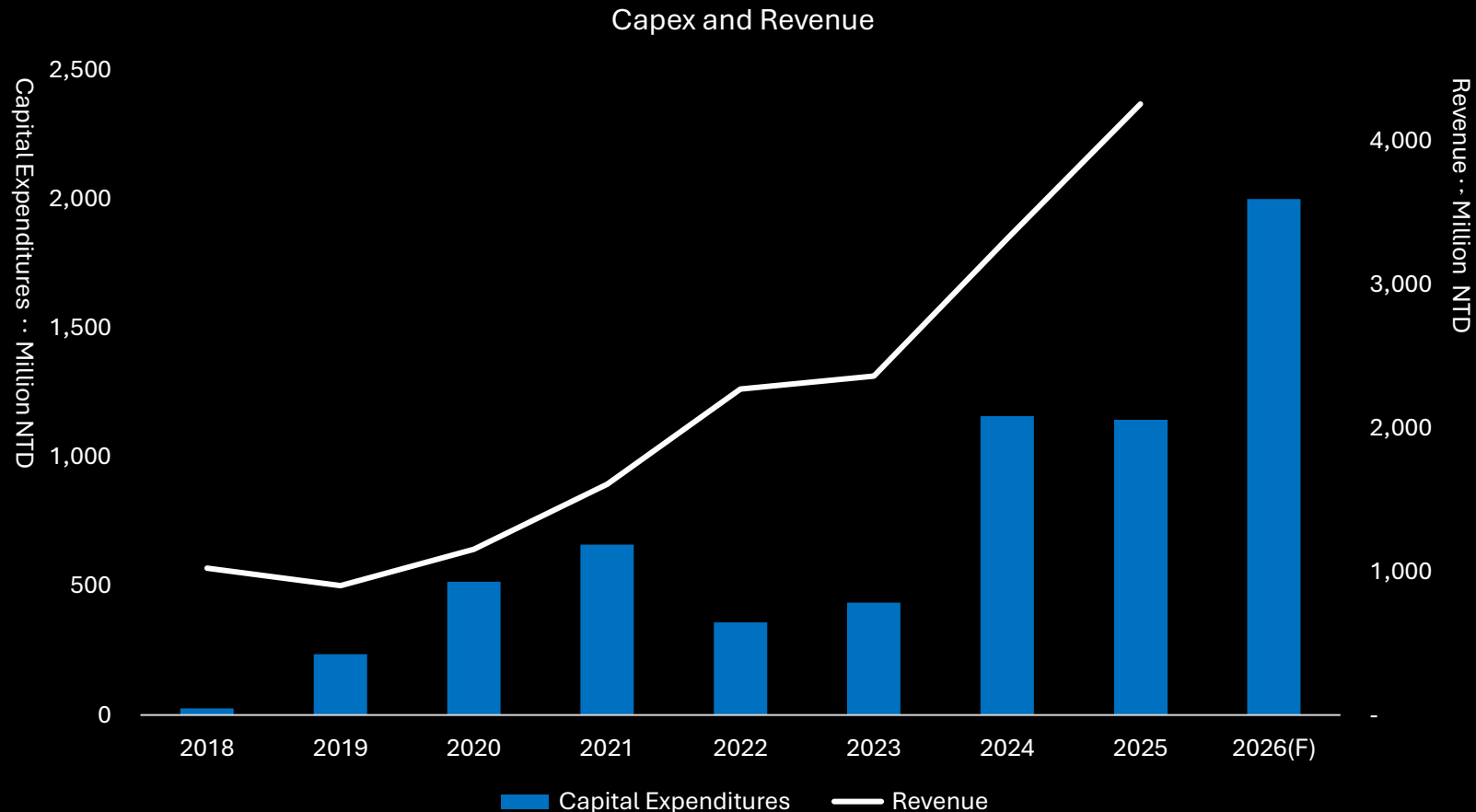


Million NTD

Year	2020	2021	2022	2023	2024	2025
Revenue	1,156	1,609	2,274	2,364	3,322	4,262
Semiconductor Material	254	773	1,503	1,627	2,634	3,708
Display Material	902	836	771	737	688	554
Gross Profit	297	422	723	694	1,204	1,835
Gross Margin	25.7%	26.2%	31.8%	29.4%	36.3%	43.1%
Operating Income	(6)	53	295	225	587	1,061
Net Income Attributable to the Parent Company	13	122	404	318	698	1,044
EPS (NT\$)	0.21	1.62	5.01	3.91	8.50	11.33

Capital Expenditures

Since 2018, AEMC has invested over NTD 4 billion in capital expenditures to support its transition into semiconductor materials development by the end of 2025.



ESG Performance



Social Engagement

Energy Efficiency and Carbon Reduction

Carbon Reduction

Talent Sustainability

Corporate Governance

Friendly Workplace



Employees voluntarily organize and participate in ESG activities.

Completed greenhouse gas inventory ahead of regulatory schedule and obtained a statement from a third-party verification body in 2024.

Awarded a certificate of appreciation by a major wafer foundry customer for the 'Supplier Energy Saving and Carbon Reduction Guidance Program

Established the 'AEMC Scholarship'

Founded the 'New Immigrant Children Scholarship'

Actively participated in 'Industry-Academia Cooperation

4 Independent directors, accounting for more than 44%
2 Female directors, accounting for more than 22%

Published Our First Sustainability Report in 2025

Female employees > 35%
Female Executives and Managers > 35%

The background of the slide is a high-tech, futuristic image of a circuit board. It features glowing blue and orange lines representing data paths and binary code (0s and 1s) scattered throughout. A central, glowing blue cube-like structure is prominent, suggesting advanced technology or data processing.

Feedback & Discussion Thank you for listening.

For further information, please visit our website at:
<https://www.aemc.com.tw/>

Contact Investor Relations at:
ir@aemc.com.tw

Income Statement

NT\$ million	4Q25	3Q25	4Q24	QOQ	YOY
Net Revenue / Net Sales	1,085	1,066	915	1.8%	18.5%
Gross Profit	477	450	348	5.9%	37.0%
Gross Margin	44.0%	42.3%	38.0%	4.0%	15.7%
Operating Expenses	224	191	208	17.6%	7.9%
Operating Profit	253	259	140	-2.3%	80.7%
Operating Margin	23.3%	24.3%	15.3%	-4.1%	52.5%
Non-operating Income and Expenses	72	77	59	-7.1%	22.8%
Net Income Attributable to the Parent Company	262	290	173	-9.8%	51.1%
EPS (NT\$)	2.85	3.13	2.10	-8.9%	35.7%

Balance Sheet



NT\$ million	4Q25		3Q25		4Q24		3Q24	
	Amount	%	Amount	%	Amount	%	Amount	%
Cash and Cash Equivalents	938	9.0%	1,286	12.8%	437	8.2%	504	9.9%
Accounts Receivable	536	5.1%	552	5.5%	532	10.0%	484	9.5%
Property, Plant and Equipment	3,743	35.8%	3,120	31.0%	2,770	51.9%	2,497	48.9%
Total Assets	10,469	100.0%	10,071	100.0%	5,334	100.0%	5,107	100.0%
Current Liabilities	967	9.2%	1,018	10.1%	1,156	21.7%	1,158	22.7%
Long-term Borrowings	-	0.0%	-	0.0%	1,102	20.7%	1,036	20.3%
Total Liabilities	1,217	11.6%	1,172	11.6%	2,400	45.0%	2,339	45.8%
Total Shareholders' Equity	9,252	88.4%	8,899	88.4%	2,935	55.0%	2,768	54.2%
Key Financial Ratios								
Current Ratio	638%		606%		157%		168%	
Debt Ratio	12%		12%		45%		46%	
Net Asset Value Per Share(NT\$)	99.77		95.96		35.67		33.69	

Cash Flow Statement

NT\$ million	4Q25	3Q25	4Q24	3Q24
Beginning Cash Balance	1,778	2,569	505	477
Cash Flows from Operating Activities	215	158	264	283
Depreciation and Amortization Expenses	76	65	60	59
Capital Expenditures	(705)	(170)	(366)	(362)
Long-term Borrowings	0	0	75	204
Ending Cash Balance	965	1,778	437	505
Free Cash Flow	(490)	(11)	(101)	(78)

Note: Free Cash Flow = Cash Flows from Operating Activities – Capital Expenditures